IFIC – SiWECAL activities: gluing and more

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Outline



Part1

Draft of COB paper → noise comparison with BGAs

Part 2

- ► Preparation for resistivity studies
 - Dummy test to check viability of the tools (climatic chamber, ohmmeter) and qualitative results

Part 3

- ▶ Preparation of tools for gluing + first tests with PCBs
 - Aspiration plate in aluminum for sensor and pcb alignment (xy and z)
 - Use of an old batch of glue (EJ2189) and transparent fake wafers
 - The tools require small adaptations for the new CALICE FEV2 PCBs and the new ECAL-e flex PCBs

Part 4

▶ PCB deformations tests after temperature/humidity cycles





Part 1: COB

COB paper draft



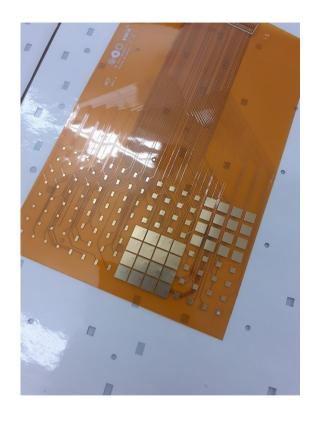
- ▶ Draft version can be found here
 - https://cernbox.cern.ch/s/ejUuYZlKthUKYMt
 - Using data from 2021/22
- ➤ Comments / corrections welcome!
- ▶ Still some sections to be written (technicalities on PCB design/production).
- ▶ Draft in NIM-A format
- "dummy" authorlist copied from old contributions

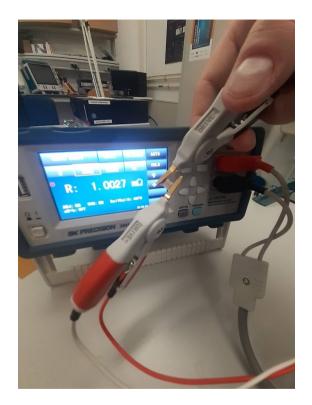


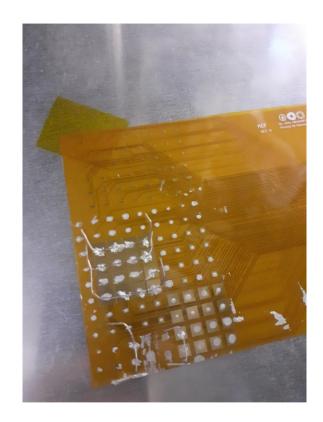


Part 2: resistivity

Dummy tests using a flex pcb (FCAL)







- ► Use EJ2189 as soldering paste
 - Solder wires to different pads (with resistivity measured)

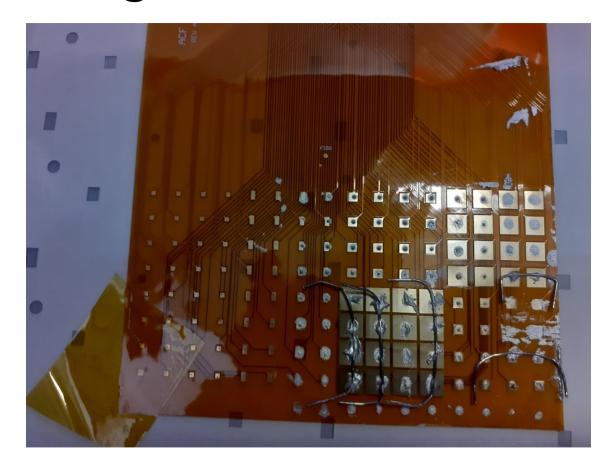




Curing in a climatic chamber





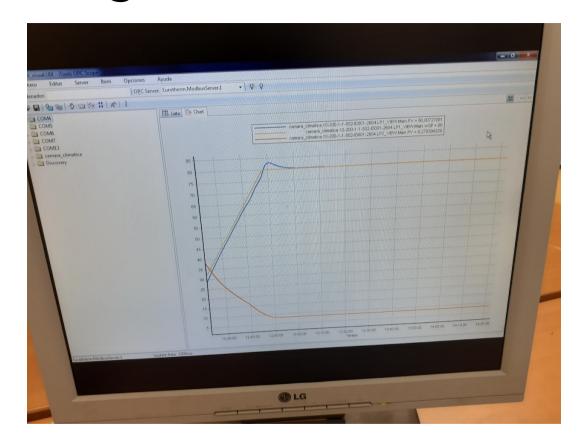


- ► Ugly result
 - But good enough to give qualitative results
- ➤ The resistivity between specific pads is measured after several humidity/temperature cycles performed





Curing in a climatic chamber





Very low humidity during the full process (10%)

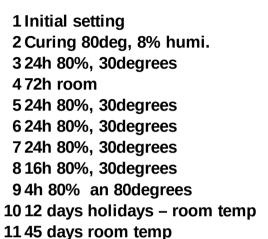


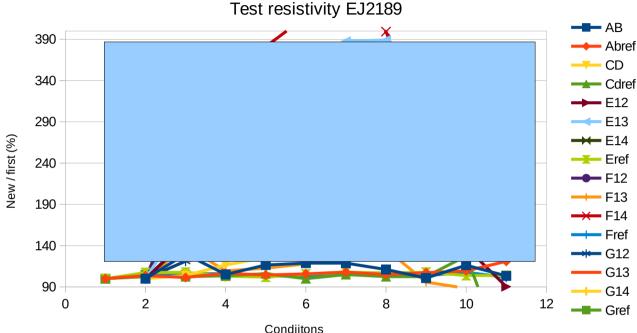




Resistivity measurements







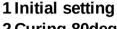
- ▶ We should look only at tendencies, not absolute values
- ▶ The G12-Gref (horizontal lines in 100%) are the reference values



Resistivity measurements







2 Curing 80deg, 8% humi.

3 24h 80%, 30degrees

472h room

5 24h 80%, 30degrees

6 24h 80%, 30degrees

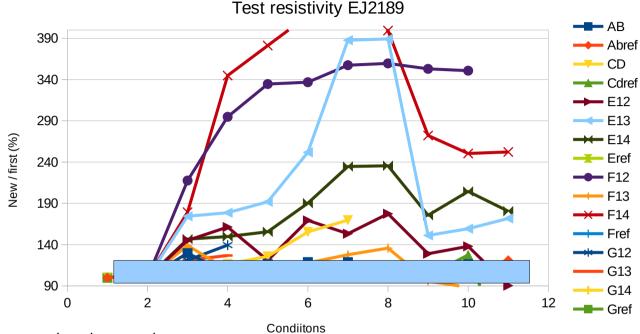
7 24h 80%, 30degrees

8 16h 80%, 30degrees

94h 80% an 80degrees

10 12 days holidays – room temp

11 45 days room temp



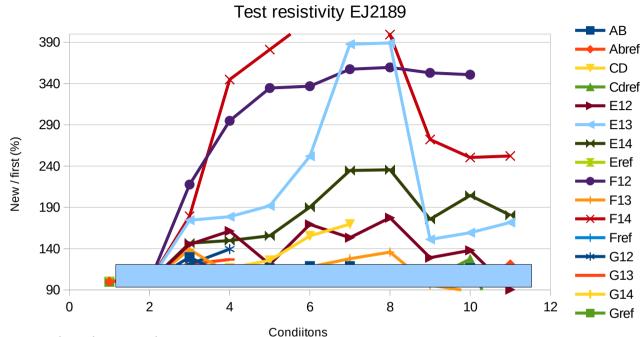
- ▶ We should look only at tendencies, not absolute values
- ▶ The G12-Gref (horizontal lines in 100%) are the reference values
- Resistivity increase after each humidity cycle



Resistivity measurements

1 Initial setting 2 Curing 80deg, 8% humi. 324h 80%, 30degrees 472h room 5 24h 80%, 30degrees 6 24h 80%, 30degrees 7 24h 80%, 30degrees 8 16h 80%, 30degrees 94h 80% an 80degrees 10 12 days holidays – room temp

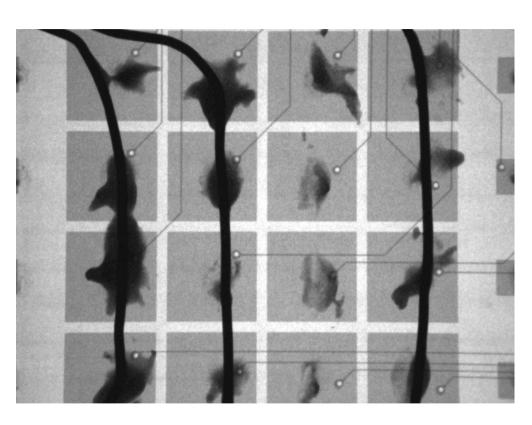
11 45 days room temp

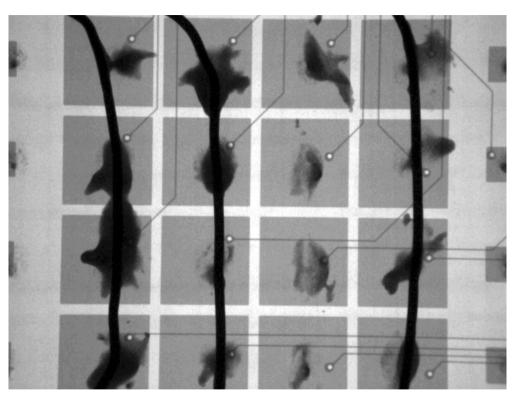


- We should look only at tendencies, not absolute values
- ▶ The G12-Gref (horizontal lines in 100%) are the reference values
- ► Resistivity increase after each humidity cycle
- Step 9: Resistivity decreased after a heat cycle (with high humidity) → re-curing?
 - The minimal requirements in the datasheet should be seen as the very minimum **LUXE**



X-rays exploration





Before curing

After all cycles

I don't appreciate any difference...





to-do





- ► This is simply an exercise...
- A proper measurement is on preparation:
 - Using new glue batches (H20E and EJ2189)
 - Using specifically designed flex PCBs (w.i.p. by Yan) and dummy silicon sensors (with the same type of aluminum plating that the real sensors)
 - Using proper tools for glue dispensing (robot or stencil...)
 - Using cold plasma gun to clean the sensors before
 - Systematic measurements and comparisons
- Lots of work which require restructuring of the lab and the new postdoc to arrive.. w.i.p.











Part 3: gluing training

Glue





- ▶ Preparing the mix
 - New equipment!



Fake wafers -xy alignment





- ► Alignment of fake transparent sensors
 - 500um

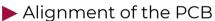




PCB -xy alignment

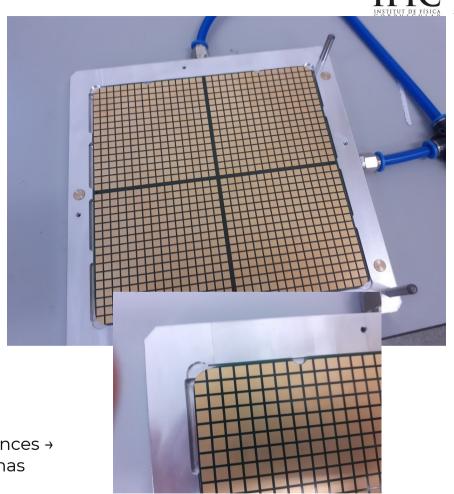






 Design of the plates optimized to FEV2 & tolerances → the FEV12 seems to be slightly larger. The PCB has been machined to fit in the plate

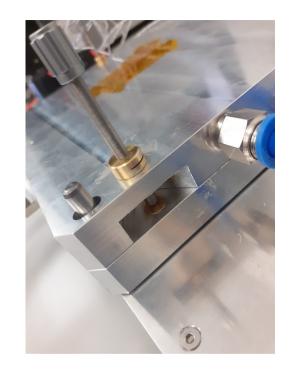
PCB without components











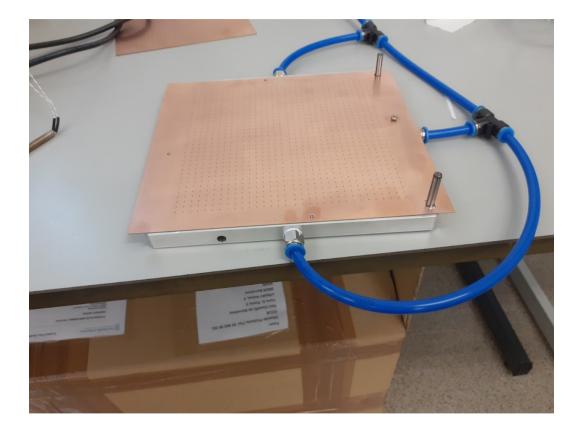
- ▶ Tuneable for each use, using precision 3 micrometric screws together with feeler gauges
- Z-alignment performed at 150um (separation between wafer and the pcb)





Glue repartition





- ► Stencil
 - 500um copper plate
 - Holes of 0.8mm diameter



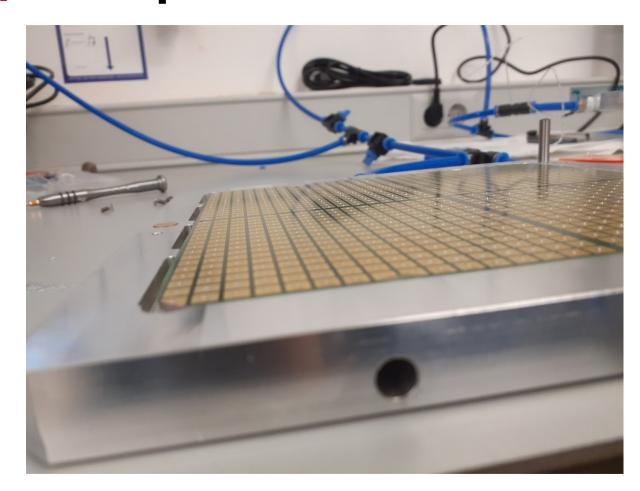
(old pic without aspiration plate)



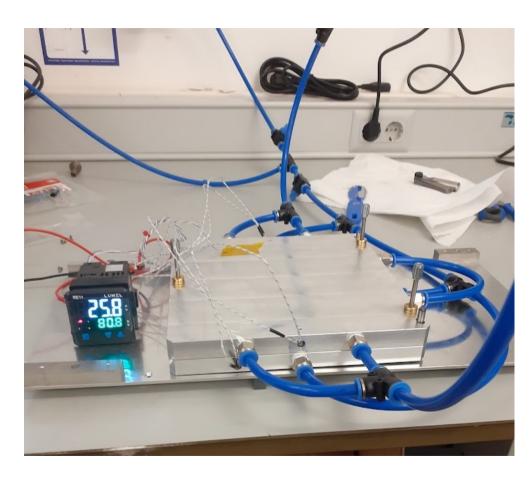


Glue repartition





For the first try, we only add glue in 3 of the 4 sectors



- ► 4 resistors (2 per aspiration plate)
- ▶ 80 degrees during 12h
 - + full weekend at room temp



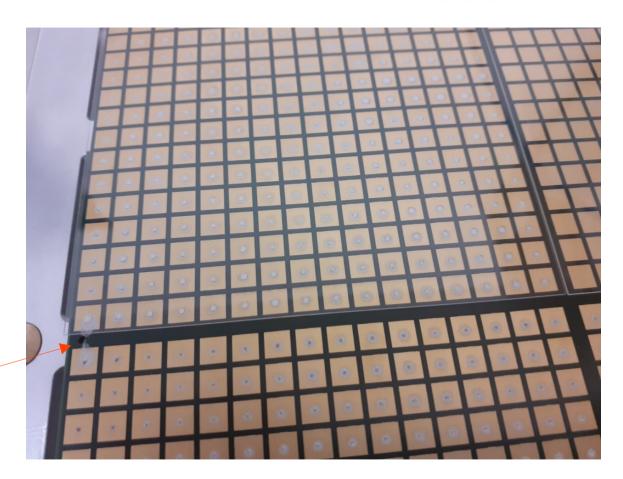


results





- Only one wafer glued (up left in the photo
 - Still small adjustments on x-y the alignment needed (but seem straightforward)
- The z-alignment seems improvable
 → more amount of glue per dot needed
 - A new test is done with 1.2mm diameter holes instead
 - This is to be better defined with the gluing robot and dosification system
- ➤ Some glue spread around PCB holes (due to the aspiration)



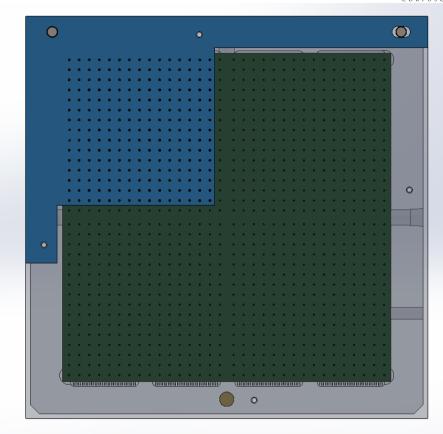




Follow up tests

- IFIC A
- 23

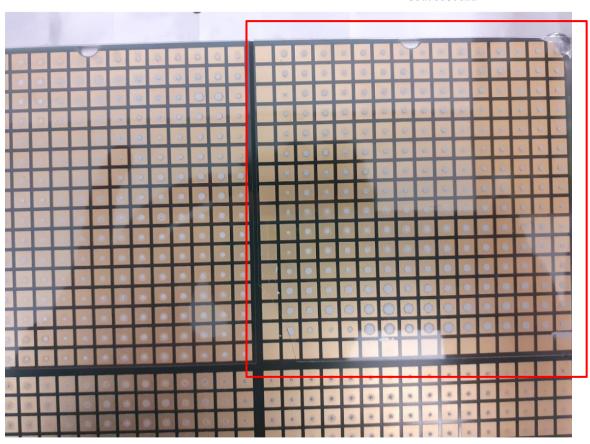
- ► Last drops of EJ2189 glue.
- ► New stencil for only one quarter
 - 1.2mm holes instead of 0.8
- ► Z-alignment performed at 150um
- ➤ Warm-up from 25 to 80 degrees took 1h15min
 - After that time, we remove the zaxis limitations of 150um
 - The plates did not move





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Summary & next steps





- ▶ The basic design of the tools and the procedire has been validated
- ► Fine tunning needed to optimize the alignment
 - Close collaboration with mechanical engineering services at IFIC (César as liason).
- > Stencil approach to be overruled by robot and volumetric dosification system (already ordered)
 - Precifluid & POLY DISPENSING SYSTEMS











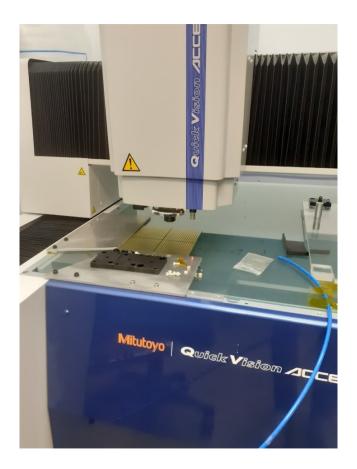
Part 4: PCB deformations

tools



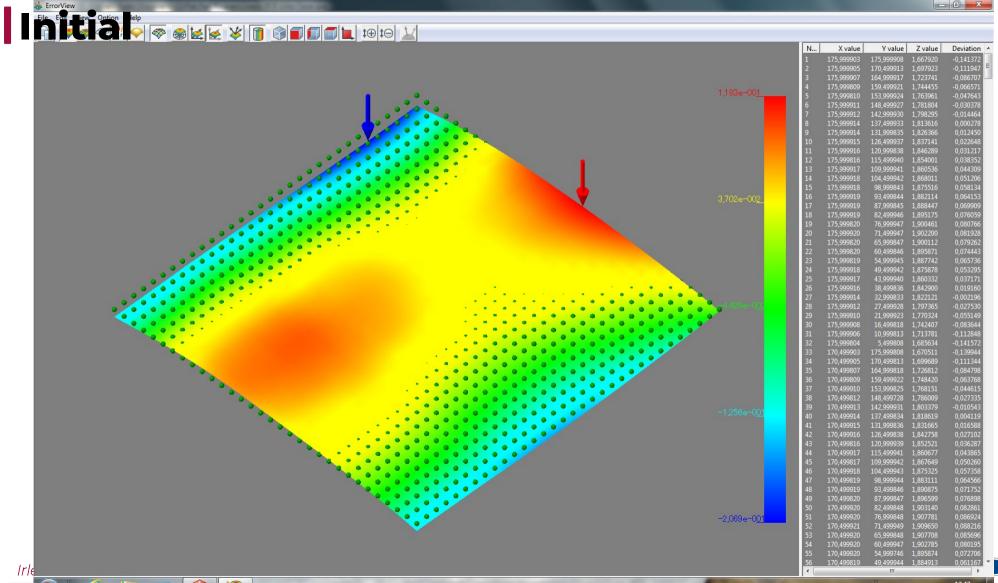


- ► FEV 12 naked
 - Not the same that we used for the glue tests.
- ► Climatic chamber
- ► Tool for z-axis characterization via optical focus
 - Mitutyo Quick Vision Accel, Modelo 808
 - https://www.mitutoyo.com/webfoo/wp-content/uploads/2118_Quick_Vision.pdf



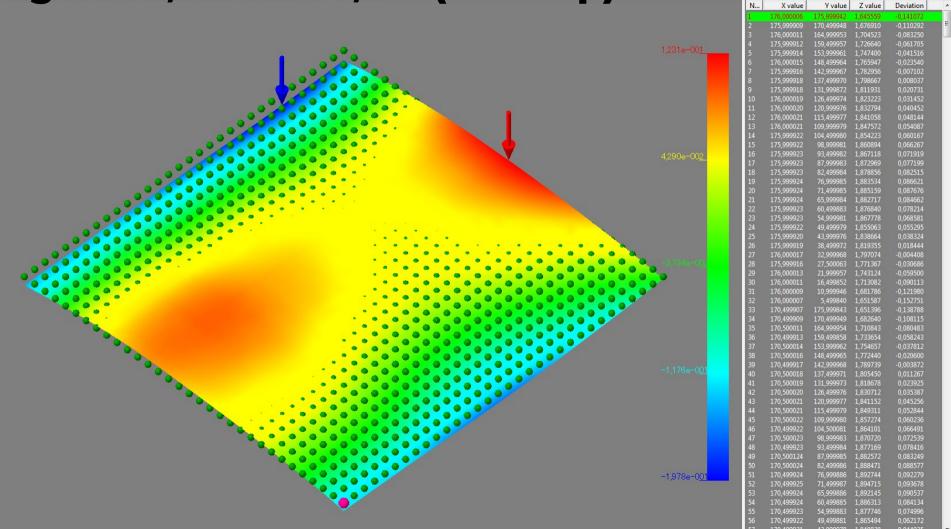






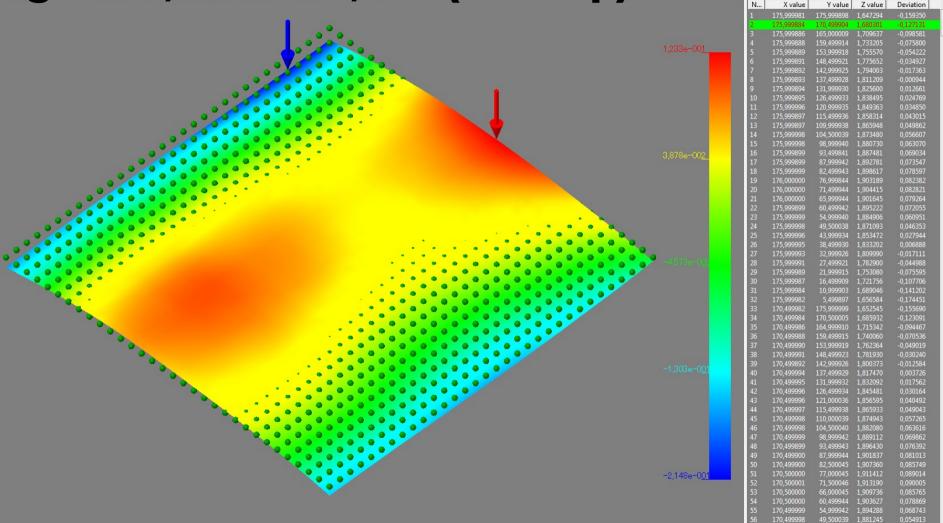


80grados, 10%hum, 3h (1h ramp)



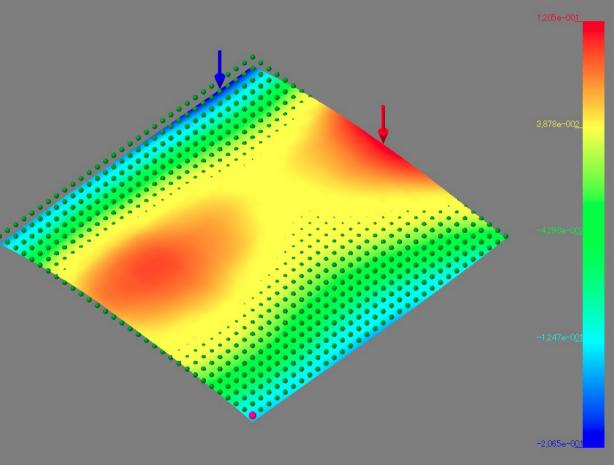


80grados, 10%hum, 12h (1h ramp)





80grados, 10%hum, 24h (1h ramp)



N	X value	Y value	Z value	Deviation	
1	175,999892	176,000028	1,639109	-0,158176	
	175,999895	170,500034	1,671495	-0,126267	
	175,999897	165,000039	1,699429	-0,098810	
	175,999898	159,499943	1,722327	-0,076389	
	175,999900	153,999947	1,743762	-0,055432	
	175,999901	148,500051	1,763329	-0,036342	
	175,999903	143,000054	1,781306	-0,018843	
8	175,999904	137,500057	1,797945	-0,002681	
9	175,999905	132,000060	1,812064	0,010960	
10	175,999906	126,499962	1,824657	0,023077	
11	175,999907	121.000064	1.834941	0,032883	
12	175,999907	115,500066	1,843810	0.041275	
13	175,999908	110,000067	1,851111	0,048098	
14	175,999908	104,500068	1,858293	0,054803	
15	175,999909	99,000070	1,865359	0,061392	
16	175.999909	93.500071	1.871977	0,067533	
17	176,000010	87,999972	1,877933	0,073011	
18	175,999910	82,500073	1,884029	0,078629	
19	175,999910	76,999974	1,888520	0,082643	
20	175,999911	71,500074	1,889769	0,083415	
21	175,999910	66,000073	1,886507	0,003413	
22	175,999910	60,499972	1,880293	0,072984	
23	175,999909	54,999970	1,870057	0,062271	
24	176,000008	49,500067	1,856454	0,002271	
25	175,999907	44,000063	1,838093	0,040190	
26	175,999905	38.500060	1.818833	0,029535	
20 27	176,000004	32,999955	1,795718	-0,009013	
18	176,000004	27,500050	1,768381	-0,015977	
29	176,000002	22,000044	1,738695	-0,041792	
30					
31	175,999997	16,499938 10.999932	1,707834	-0,103293 -0.135898	
	175,999895 175,999893		1,675707 1,644025		
32 33		5,500026		-0,168057	
	170,499993	176,000029	1,645387	-0,153449	
34 35	170,499895	170,500035	1,677186	-0,122127	
	170,499897	164,999940	1,706221	-0,093569	
36	170,499899	159,500045	1,729977	-0,070291	
37	170,499900	153,999949	1,751037	-0,049708	
38	170,499902	148,500052	1,770146	-0,031076	
39	170,500003	142,999956	1,788261	-0,013439	
10	170,499904	137,499959	1,804651	0,002474	
41	170,500005	131,999961	1,818909	0,016255	
42	170,499906	126,500064	1,831794	0,028662	
43	170,500007	121,000066	1,843006	0,039397	
44	170,499908	115,500067	1,852443	0,048356	
45	170,499908	110,000069	1,859495	0,054931	
46	170,500009	104,500070	1,867373	0,062332	
47	170,499909	99,000071	1,874447	0,068929	
48	170,499910	93,499973	1,881876	0,075880	
49	170,499910	88,000073	1,886937	0,080464	
50	170,499911	82,500074	1,893032	0,086082	
51	170,499911	77,000075	1,897377	0,089949	
52	170,499911	71,499975	1,898964	0,091059	
53	170,499911	66,000075	1,895811	0,087428	
54	170,499911	60,500073	1,889073	0,080213	
55	170,499910	54,999971	1,879797	0,070459	
56	170,500009	49,499969	1,866417	0,056603	





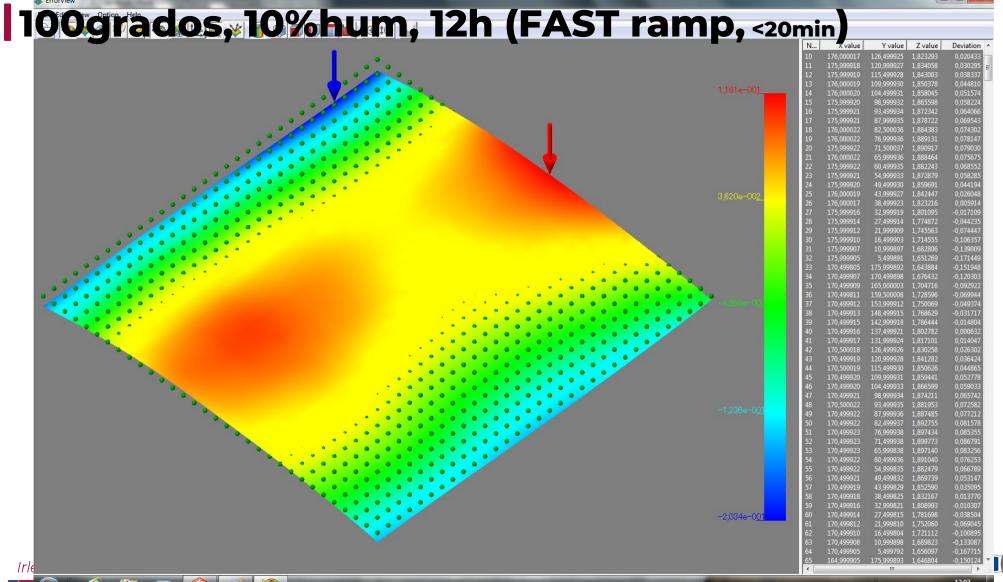






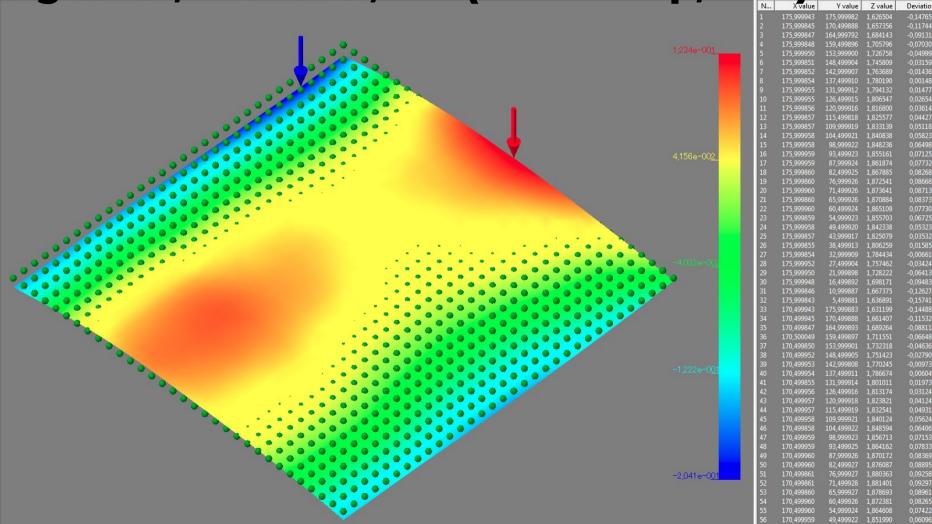








80grados, 80%hum, 12h (FAST ramp, <20min)





results





- ▶ Basically no extra deformation observed after the cycles
- But an initial +120um, -200um deformation from the middle plane
- Curing at 100degrees may not be an issue at all.
 - Tests done without sensors/components!
- ► Would this PCB have been used for gluing sensors?
 - The aspiration plate was capable of support it removing the deformation....

back-up





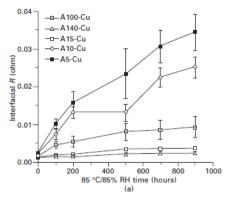


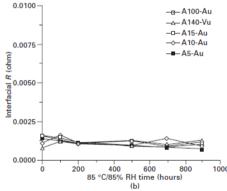
Tests to be done January-April 2023





- ➤ We have purchased a set of dummy substrates with aluminum and gold bath (as the Hammatsu sensors)
 - Delivery in ~ January
- ➤ We have orderd the epoxys (still waiting for the note on the gold based).
 - Delivery in January-February
- ➤ Yan is designing a special kapton fanout to be glued to the dummy sensors and perform resitance measurements of the glue dots.
 - Using a precision ohmemetre to measure mOhms.
 - Production/delivery?March?
- ➤ We are getting trained in the use of a climatic chamber here at IFIC: the idea is to tests the different glues and surfaces after several humidity cycles and check the resistivity.
- ► Also access to a x-ray machine for a "visual" inspection.





4.9 Ag ICA contact resistance changes at 85/85: (a) on Cu contacts, (b) on Au contacts, with (c) corresponding bulk resistivity variations.

Bibliography reference on epoxy+silver glues performance (attached to the agenda)

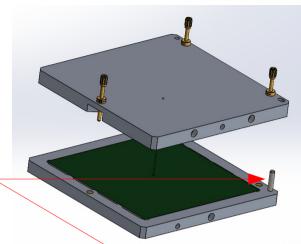


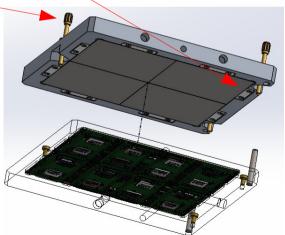


aspiration plates design

- ➤ Sandwich-maker style
- ► Two aspiration plates
 - One for the wafers
 - One for the PCBs (with components in it)
- ▶ Alignment in x-y done by the aspirations themselves and pivot tools
- ► Alignment in z done with micrometric screws
 - To deal with the PCB thickness tolerances (of possible hundreds of um)









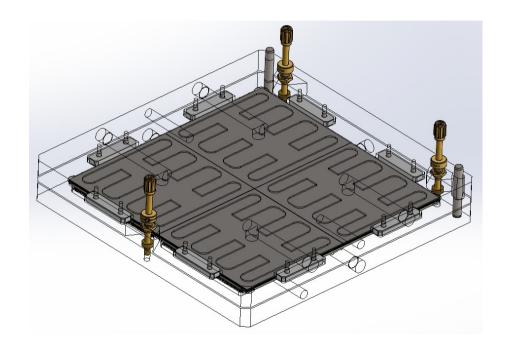


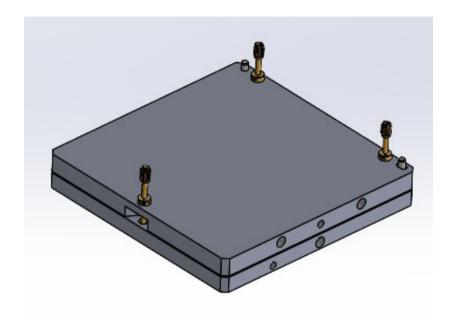


Activity 1 – aspiration plates design











Activity 1 – aspiration plates design





▶ Also thermal curing using resistance and APDs for temperature control

